



## Material Content Data Sheet



<b>Sales Product Name</b>		BCR 108 E6327		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000962012						
<b>Package</b>		PG-SOT23-3-11		<b>Weight*</b>		8.80 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.005	0.06		569	
	non noble metal	arsenic	7440-38-2	0.000	0.00		6	
	inorganic material	silicon	7440-21-3	0.043	0.49	0.55	4862	5437
leadframe	non noble metal	chromium	7440-47-3	0.008	0.09		926	
	inorganic material	silicon	7440-21-3	0.001	0.01		62	
	non noble metal	titanium	7440-32-6	0.003	0.03		309	
	non noble metal	copper	7440-50-8	2.704	30.72	30.85	307231	308528
wire	noble metal	gold	7440-57-5	0.011	0.13	0.13	1302	1302
encapsulation	organic material	carbon black	1333-86-4	0.058	0.66		6566	
	plastics	brominated resin	-	0.087	0.98		9849	
	inorganic material	antimonytrioxide	1309-64-4	0.116	1.31		13132	
	plastics	epoxy resin	-	1.243	14.12		141167	
	inorganic material	silicondioxide	60676-86-0	4.277	48.59	65.66	485876	656590
leadfinish	non noble metal	tin	7440-31-5	0.150	1.70	1.70	17001	17001
plating	noble metal	silver	7440-22-4	0.098	1.11	1.11	11142	11142
*deviation	< 10%		Sum in total:			100,00		1000000

### Important Remarks:

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